



Material Content Data Sheet



Sales Product Name	TLE9832QX			Issued		21. September 2015		
MA#	MA001408908							
Package	PG-VQFN-48-29			Weight*		130.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.983	3.83	3.83	38258	38258
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		550	
	non noble metal	iron	7439-89-6	1.433	1.10		11003	
	non noble metal	copper	7440-50-8	58.193	44.67	45.84	446775	458466
wire	noble metal	gold	7440-57-5	0.782	0.60	0.60	6007	6007
encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1388	
	plastics	epoxy resin	-	7.656	5.88		58778	
	inorganic material	silicondioxide	60676-86-0	52.446	40.26	46.28	402650	462816
leadfinish	non noble metal	tin	7440-31-5	2.629	2.02	2.02	20183	20183
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4713	4713
glue	plastics	epoxy resin	-	0.286	0.22		2198	
	noble metal	silver	7440-22-4	0.958	0.74	0.96	7359	9557
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com